



SGMICRO 10MHz, 1A Micro-Point-of-Load Buck Converter

SGM61013

GENERAL DESCRIPTION

The Micro-Point-of-Load (μ POL) SGM61013 is a family of high-efficient and high-frequency Buck DC/DC converter. Operating with a switching frequency up to 10MHz, it allows the use of small external components in both value and footprint. Different versions are available with fixed output voltages of 1.2V, 1.8V and 3.3V, delivered from an input voltage supply of 2.3V to 5.5V. A low quiescent current of only 20 μ A (TYP) enables high efficiency even with very light loads.

At light current load condition, the converter will automatically enter pulse frequency modulation (PFM) mode for best possible efficiency over the entire range of load currents. If PFM mode is not desired, the MODE pin can be set high to forced pulse width modulation (FPWM) operation.

The SGM61013 is available in a Green WLCSP-0.9 \times 1.2-6B package.

FEATURES

- 2.3V to 5.5V Input Voltage Range
- SGM61013A: 1.8V Fixed Output Voltage
- SGM61013B: 1.2V/3.3V Fixed Output Voltages
- 1A Output Current
- 20 μ A (TYP) Quiescent Current
- Up to 95% Efficiency
- Selectable PFM Light Load Operation
- Fast Load Transient Response
- 100% Duty Cycle
- Logic Enable Input
- Soft-Start
- Input Under-Voltage Lockout
- Over-Current Protection
- Thermal Shutdown
- Active Output Discharge
- Available in a Green WLCSP-0.9 \times 1.2-6B Package

APPLICATIONS

- Optical Modules
- Cellular Phones
- Tablets
- Wireless Data Cards

- Embedded Power Supply
- Wearables
- IoT
- Security and Surveillance

TYPICAL APPLICATION

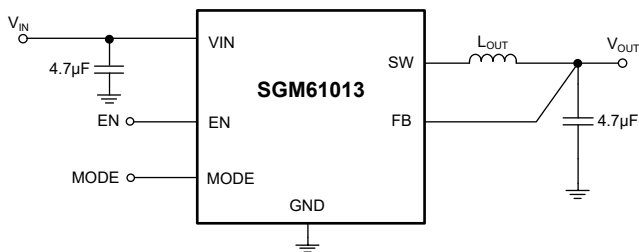
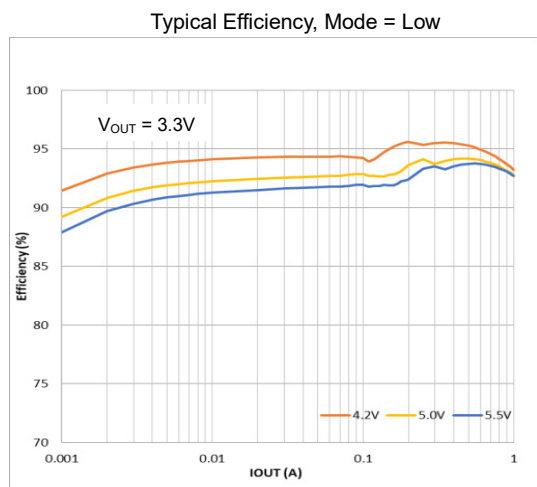


Figure 1. Typical Application Circuit

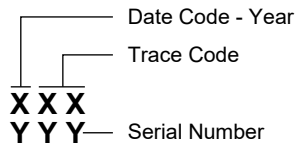


PACKAGE/ORDERING INFORMATION

MODEL	V _{OUT} (V)	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM61013A (10MHz)	1.8	WLCSP-0.9×1.2-6B	-40°C to +85°C	SGM61013A-1.8YG/TR	XXX G9S	Tape and Reel, 3000
SGM61013B (6.5MHz)	1.2	WLCSP-0.9×1.2-6B	-40°C to +85°C	SGM61013B-1.2YG/TR	XXX G9U	Tape and Reel, 3000
SGM61013B (8MHz)	3.3	WLCSP-0.9×1.2-6B	-40°C to +85°C	SGM61013B-3.3YG/TR	XXX GAH	Tape and Reel, 3000

MARKING INFORMATION

NOTE: XXX = Date Code and Trace Code.



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS

- DC Supply Voltage..... -0.3V to 6V
- Voltage on Other Pins, MODE, SW, FB, EN-0.3V to V_{IN} + 0.3V
- Package Thermal Resistance
- WLCSP-0.9×1.2-6B, θ_{JA} 130°C/W
- Junction Temperature.....+150°C
- Storage Temperature Range -65°C to +150°C
- Lead Temperature (Soldering, 10s).....+260°C
- ESD Susceptibility
- HBM.....±4000V
- CDM±2000V

RECOMMENDED OPERATING CONDITIONS

- Supply Voltage..... 2.3V to 5.5V⁽¹⁾
- Output Current.....0A to 1.0A
- Output Inductor..... 220nH to 2200nH, 470nH (TYP)
- Input Capacitor2.2µF to 4.7µF (TYP)
- Output Capacitor.....2.2µF to 4.7µF (TYP)
- Operating Ambient Temperature Range..... -40°C to +85°C
- Operating Junction Temperature Range..... -40°C to +125°C

NOTE:

1. V_{IN} above 5.5V over extended periods may affect device reliability.

OVERSTRESS CAUTION

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

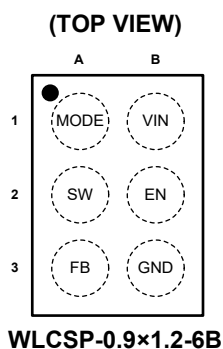
ESD SENSITIVITY CAUTION

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

PIN CONFIGURATION



PIN DESCRIPTION

PIN	NAME	DESCRIPTION
A1	MODE	Mode Selection. MODE pin = Low allows the converter to automatically switch between pulse frequency modulation (PFM) at light current loads and pulse width modulation (PWM) at heavy current loads. MODE pin = High forces the converter to stay in PWM mode.
B1	VIN	Power Supply Input. Connect to power source with a minimum 2.2 μ F ceramic capacitor.
A2	SW	Switching Node. Connect to the output inductor.
B2	EN	Enable Logic Input. Logic high level ($V_{EN} > 1.2V$) enables the device. Logic low level ($V_{EN} < 1.07V$) disables the device and turns it into shutdown mode. Do not leave this pin floating.
A3	FB	Feedback Input. Connect to output voltage.
B3	GND	Ground Pin.

ELECTRICAL CHARACTERISTICS

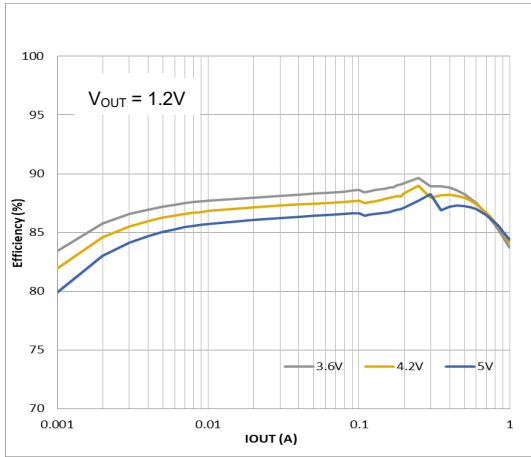
(Typical values are at $V_{IN} = 3.6V$, $V_{OUT} = 1.8V$, $MODE = 0V$, $T_A = +25^{\circ}C$, maximum and minimum values are at $V_{IN} = V_{EN} = 2.3V$ to $5.5V$, $T_A = -40^{\circ}C$ to $+85^{\circ}C$, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DC Characteristics						
Supply Voltage	V_{IN}		2.3		5.5	V
Quiescent Current	I_Q	PWM mode		6.5		mA
		No load, not switching		20		μA
Shutdown Current	I_{SHDN}	EN = GND		0.1	1	μA
Under-Voltage Lockout Threshold	V_{UVLO}	Rising V_{IN}		2.0	2.25	V
Under-Voltage Lockout Hysteresis	$V_{UVLOHYS}$			150		mV
Thermal Shutdown	T_{TSD}			135		$^{\circ}C$
Thermal Shutdown Hysteresis	T_{HYST}			15		$^{\circ}C$
Output Characteristics						
Switching Frequency	F_{SW}	SGM61013B-1.2		6.5		MHz
		SGM61013B-3.3		8		
		SGM61013A-1.8		10		
Output Voltage Accuracy	V_{OUT}	$I_{LOAD} = 0A$ to $1A$, $V_{IN} = 5.5V$ (MAX)	-2%	V_{OUT}	+2%	
		PWM Mode, $V_{IN} = 5.5V$ (MAX)	-1.5%	V_{OUT}	+1.5%	
Soft-Start Time	t_{SS}			280		μs
Enable Turn-on Delay	t_{EN}			100		μs
PMOS On-Resistance	R_{DSON_P}	$V_{IN} = V_{GS} = 3.6V$		148		m Ω
NMOS On-Resistance	R_{DSON_N}	$V_{IN} = V_{GS} = 3.6V$		77		m Ω
PMOS Peak Current Limit	I_{LIM}	$V_{IN} = 3.6V$, open loop		1600		mA
Output Discharge Resistance	R_{DIS}	$V_{EN} = 0V$		17		Ω
Logic Inputs: EN and Mode						
Logic High Voltage	V_{IH}		1.2		V_{IN}	V
Logic Low Voltage	V_{IL}				1.07	V
Logic Pin Leakage Current	I_{LPIN}				1	μA
Logic Input Hysteresis	V_{LHYS}			130		mV

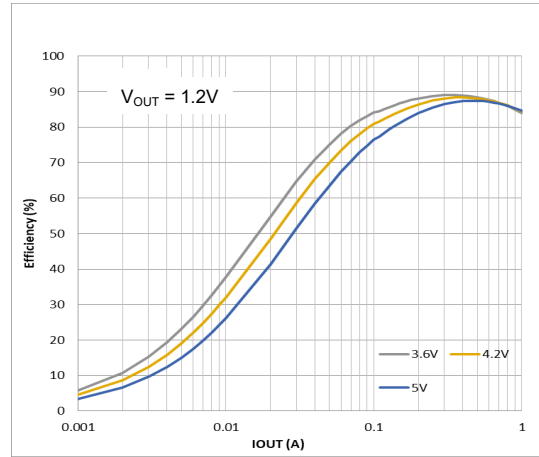
TYPICAL PERFORMANCE CHARACTERISTICS

$V_{IN} = 3.6V$, $V_{OUT} = 1.8V$. MODE = 0V, $T_A = +25^{\circ}C$. $F_{SW} = 10MHz$ for 1.8V device, $F_{SW} = 6.5MHz$ for 1.2V and $F_{SW} = 8MHz$ for 3.3V devices, unless otherwise noted.

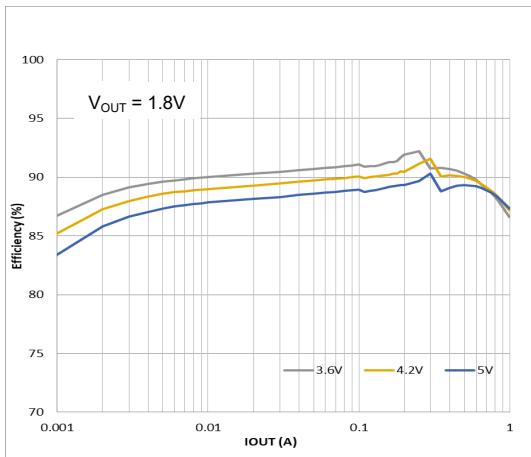
Efficiency, Mode = Low



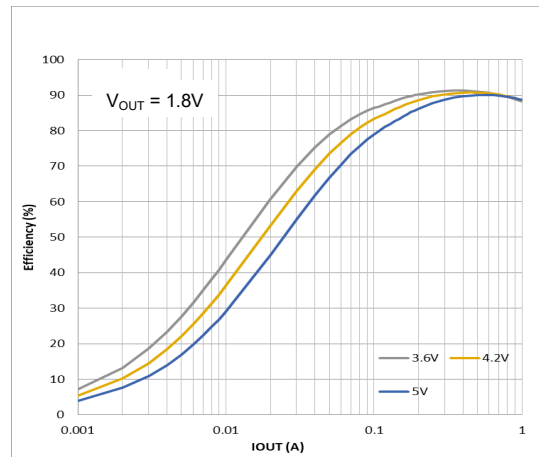
Efficiency, Mode = High



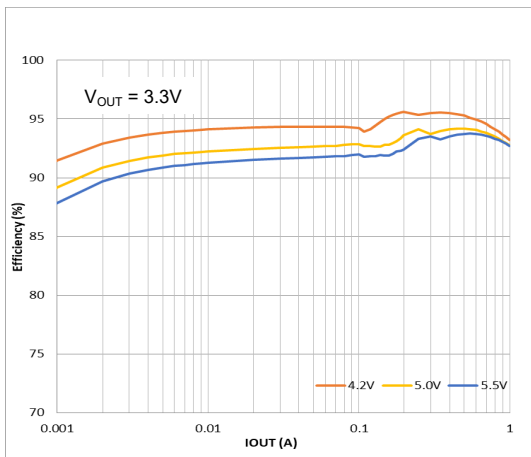
Efficiency, Mode = Low



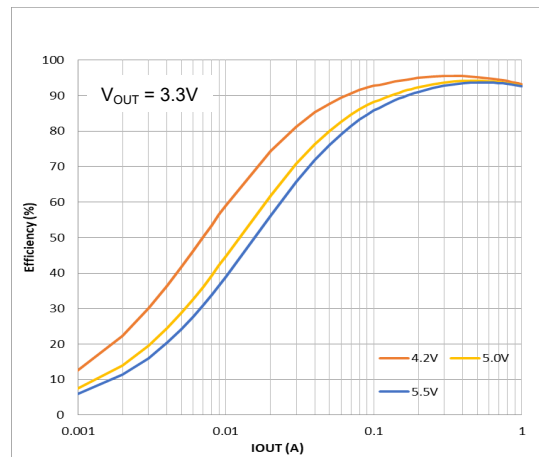
Efficiency, Mode = High



Efficiency, Mode = Low



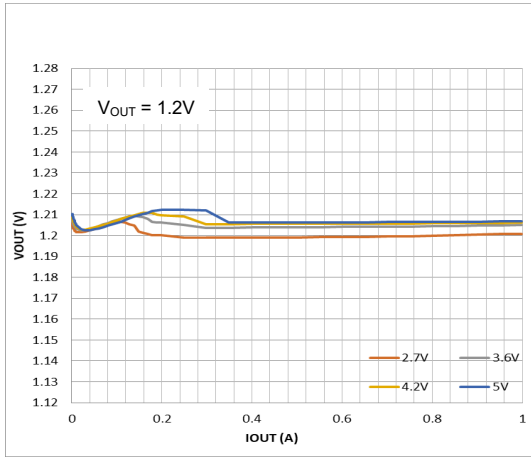
Efficiency, Mode = High



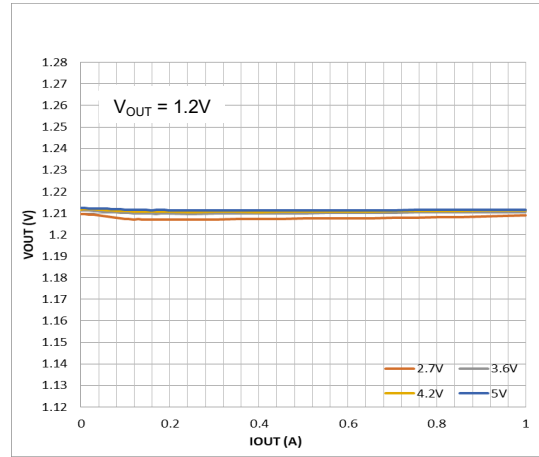
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

$V_{IN} = 3.6V$, $V_{OUT} = 1.8V$. MODE = 0V, $T_A = +25^{\circ}C$. $F_{SW} = 10MHz$ for 1.8V device, $F_{SW} = 6.5MHz$ for 1.2V and $F_{SW} = 8MHz$ for 3.3V devices, unless otherwise noted.

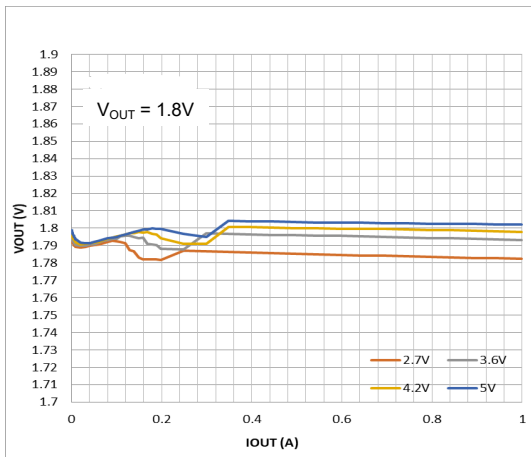
Load Regulation, Mode = Low



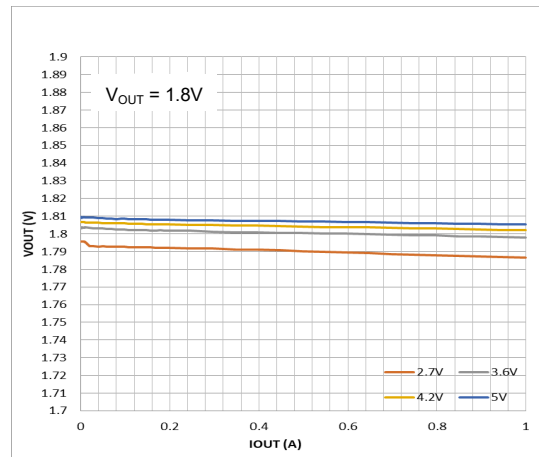
Load Regulation, Mode = High



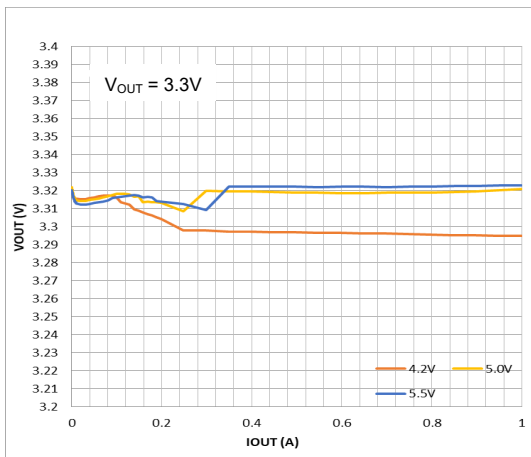
Load Regulation, Mode = Low



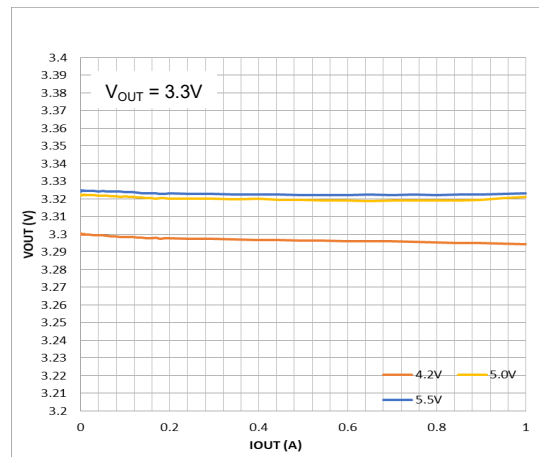
Load Regulation, Mode = High



Load Regulation, Mode = Low



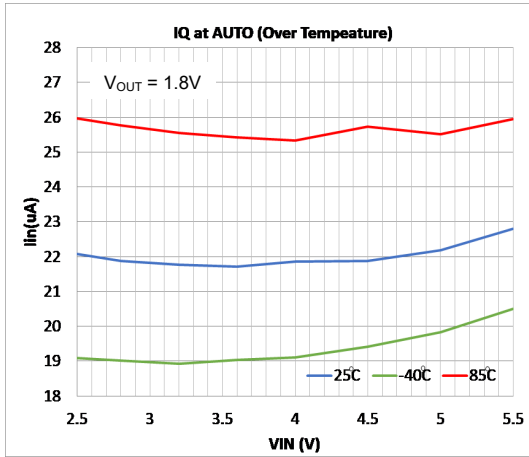
Load Regulation, Mode = High



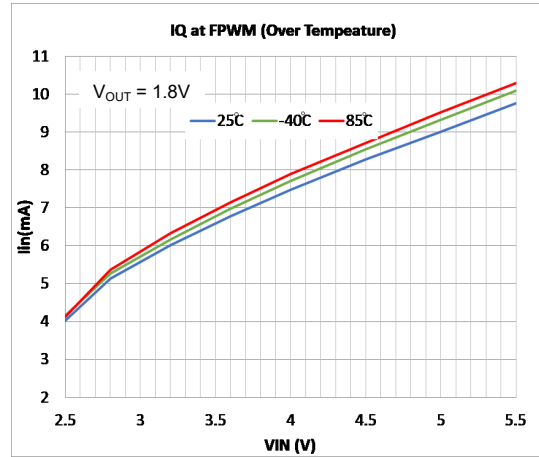
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

$V_{IN} = 3.6V$, $V_{OUT} = 1.8V$. MODE = 0V, $T_A = +25^\circ C$. $F_{SW} = 10MHz$ for 1.8V device, $F_{SW} = 6.5MHz$ for 1.2V and $F_{SW} = 8MHz$ for 3.3V devices, unless otherwise noted.

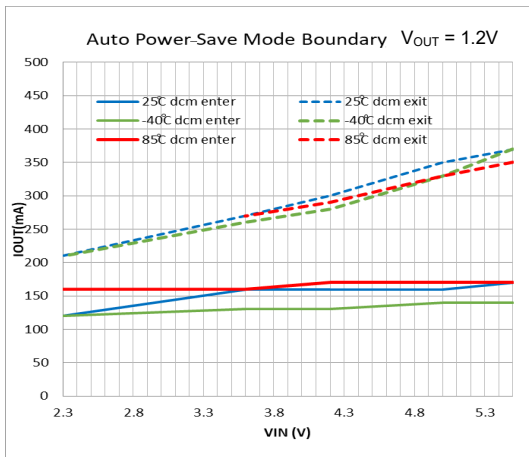
I_Q vs. V_{IN} over Temperature, Mode = Low



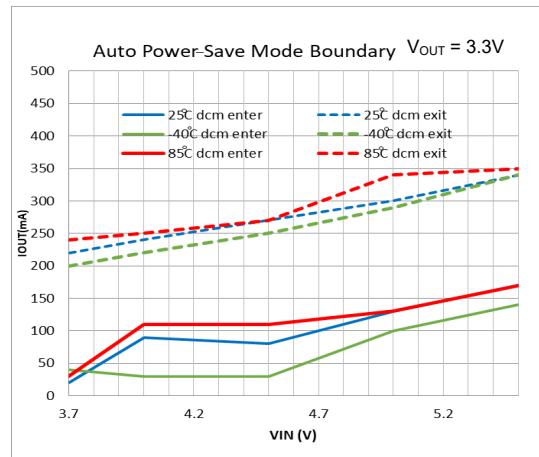
I_Q vs. V_{IN} over Temperature, Mode = High



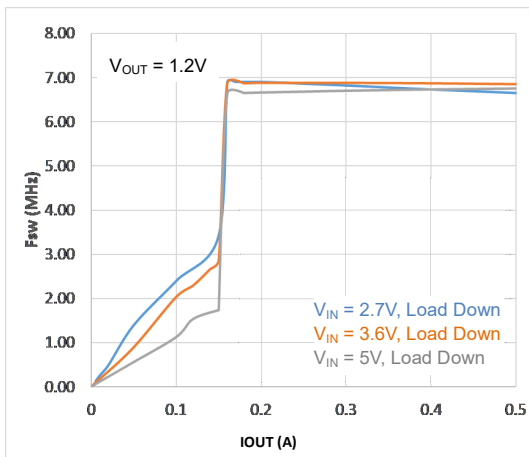
PFM/PWM Boundaries, Mode = Low



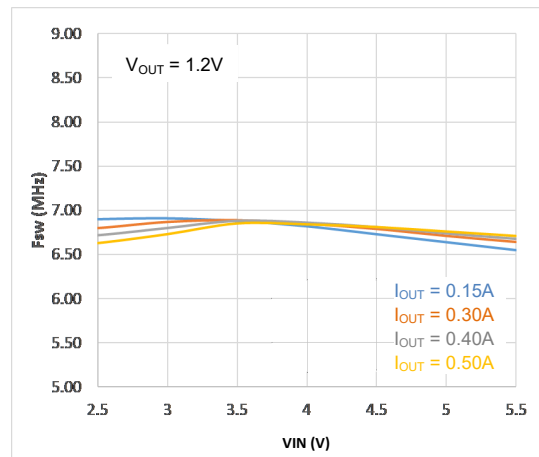
PFM/PWM Boundaries, Mode = Low



Switching Frequency, Mode = Low



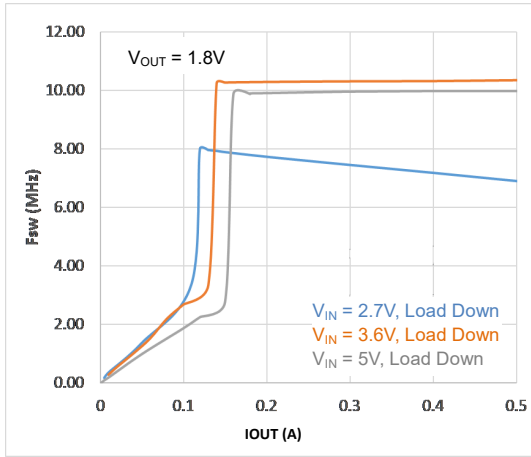
Switching Frequency, Mode = High



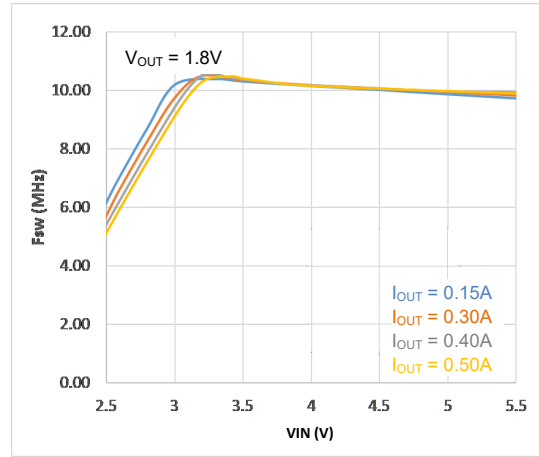
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

$V_{IN} = 3.6V$, $V_{OUT} = 1.8V$. MODE = 0V, $T_A = +25^\circ C$. $F_{SW} = 10MHz$ for 1.8V device, $F_{SW} = 6.5MHz$ for 1.2V and $F_{SW} = 8MHz$ for 3.3V devices, unless otherwise noted.

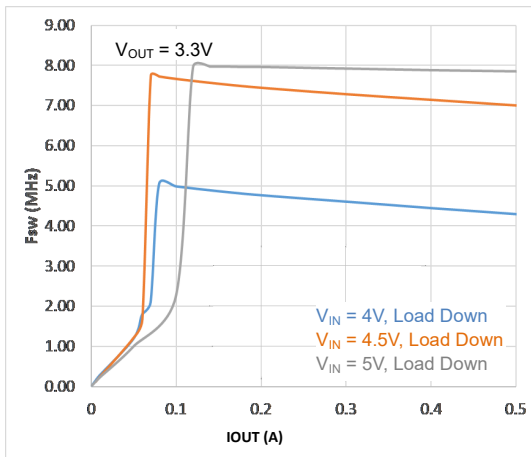
Switching Frequency, Mode = Low



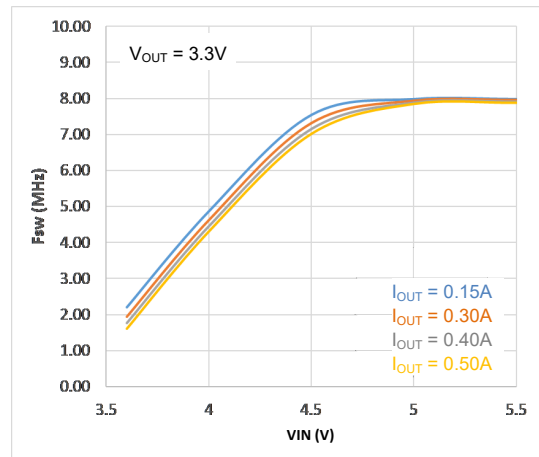
Switching Frequency, Mode = High



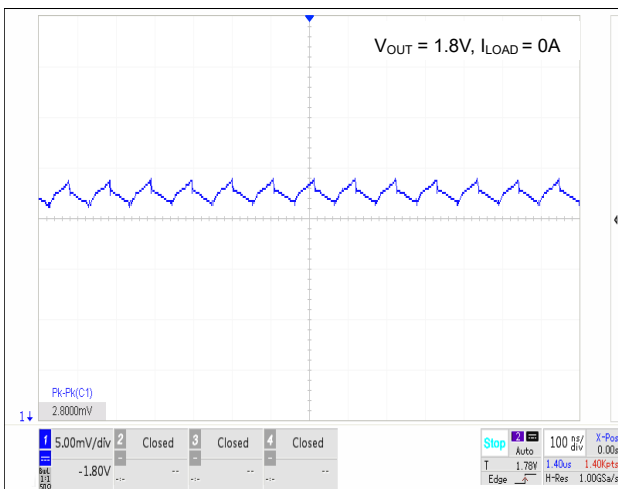
Switching Frequency, Mode = Low



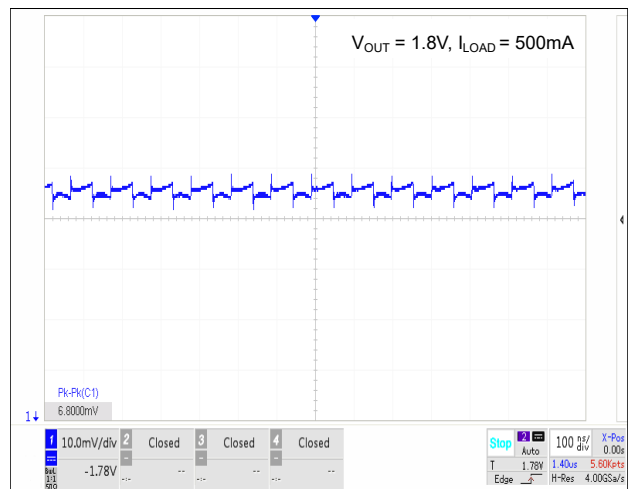
Switching Frequency, Mode = High



Output Voltage Ripple, Mode = High



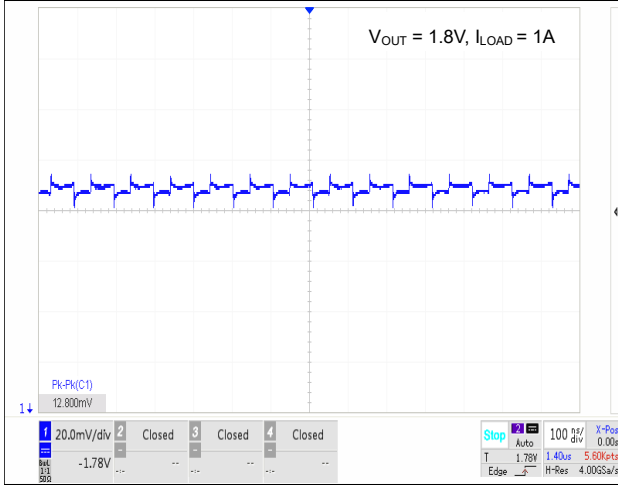
Output Voltage Ripple, Mode = High



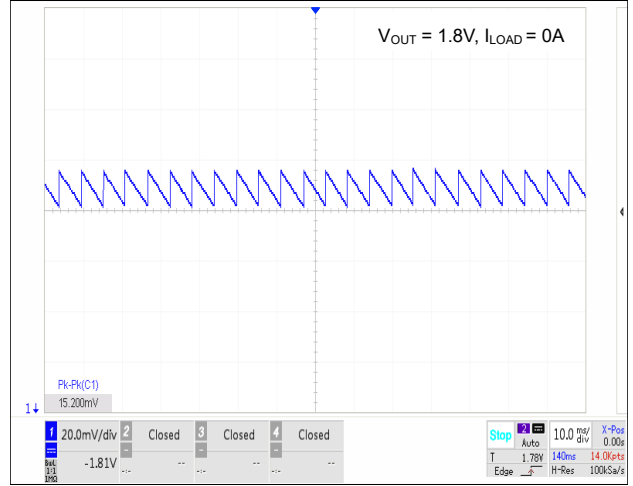
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

$V_{IN} = 3.6V$, $V_{OUT} = 1.8V$. MODE = 0V, $T_A = +25^\circ C$. $F_{SW} = 10MHz$ for 1.8V device, $F_{SW} = 6.5MHz$ for 1.2V and $F_{SW} = 8MHz$ for 3.3V devices, unless otherwise noted.

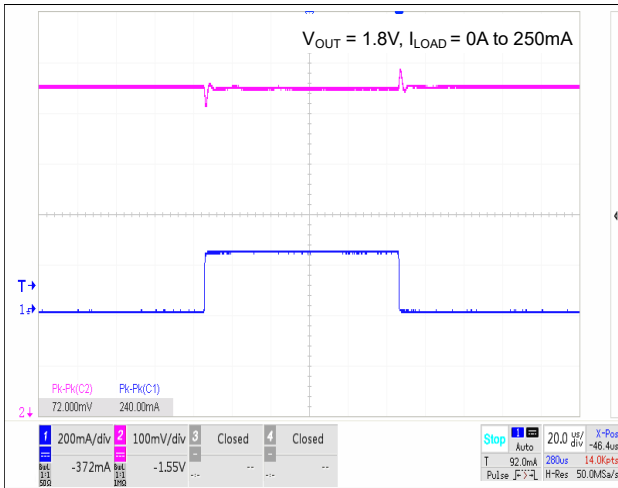
Output Voltage Ripple, Mode = High



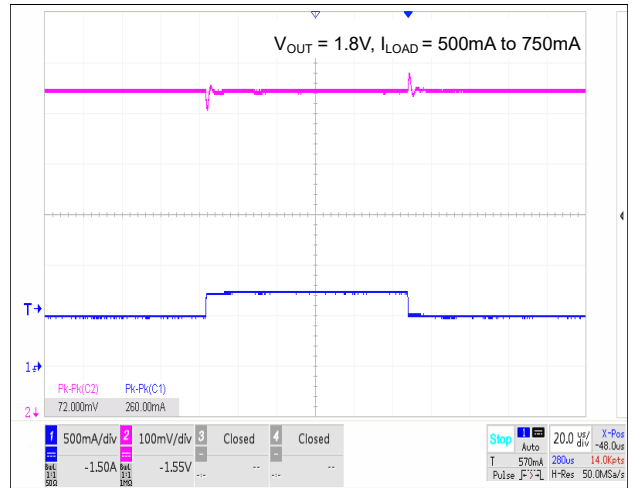
Output Voltage Ripple, Mode = Low



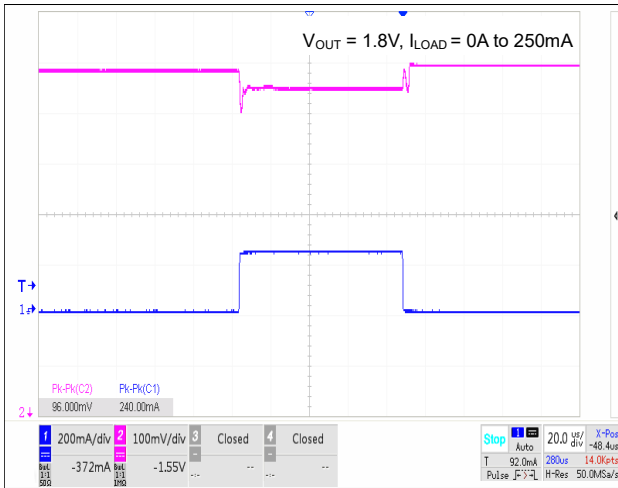
Load Transient, Mode = High



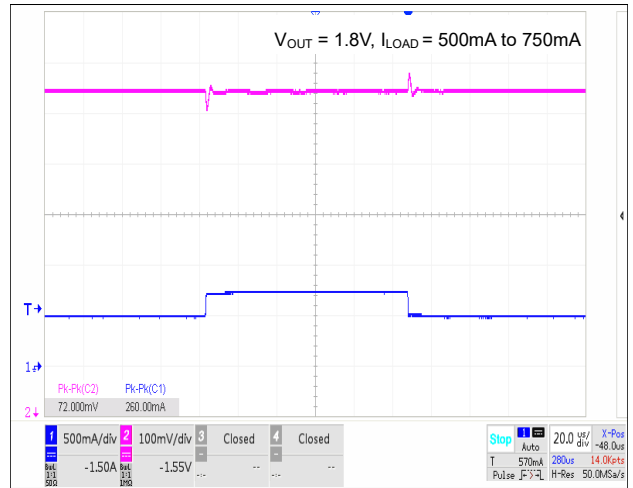
Load Transient, Mode = High



Load Transient, Mode = Low



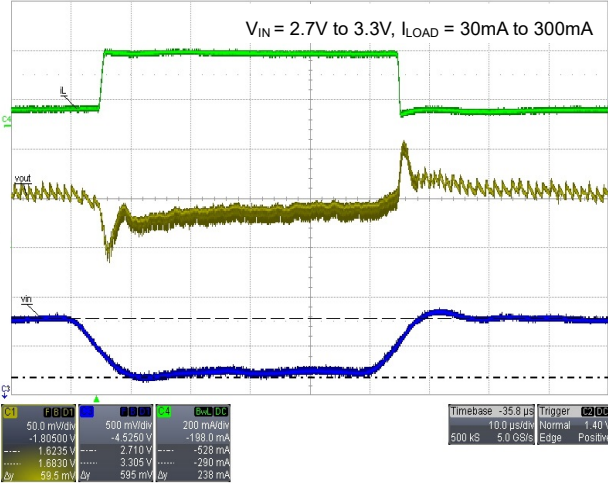
Load Transient, Mode = Low



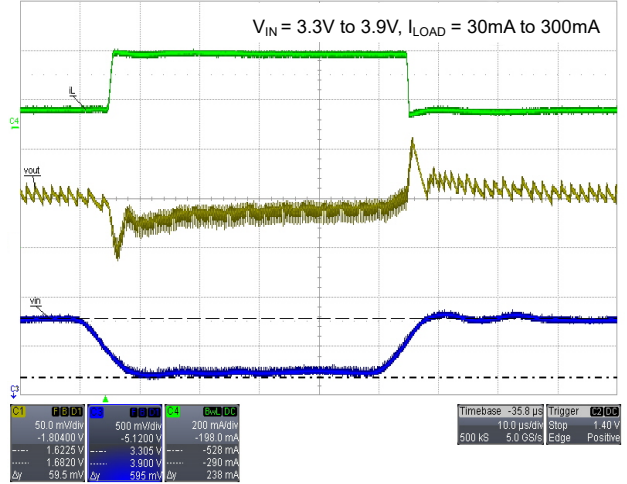
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

$V_{IN} = 3.6V$, $V_{OUT} = 1.8V$. MODE = 0V, $T_A = +25^\circ C$. $F_{SW} = 10MHz$ for 1.8V device, $F_{SW} = 6.5MHz$ for 1.2V and $F_{SW} = 8MHz$ for 3.3V devices, unless otherwise noted.

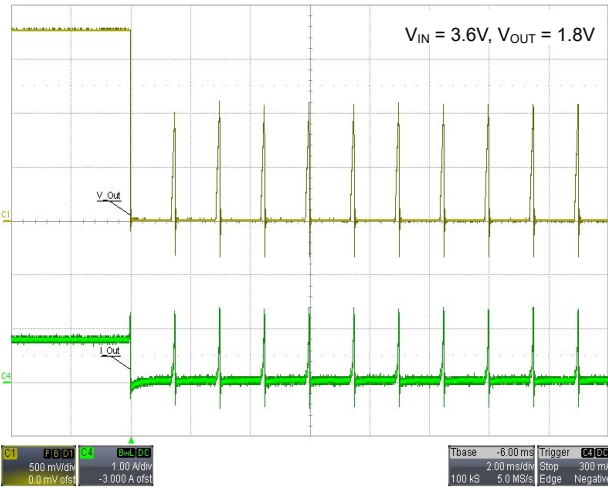
Combined Line/Load Transient



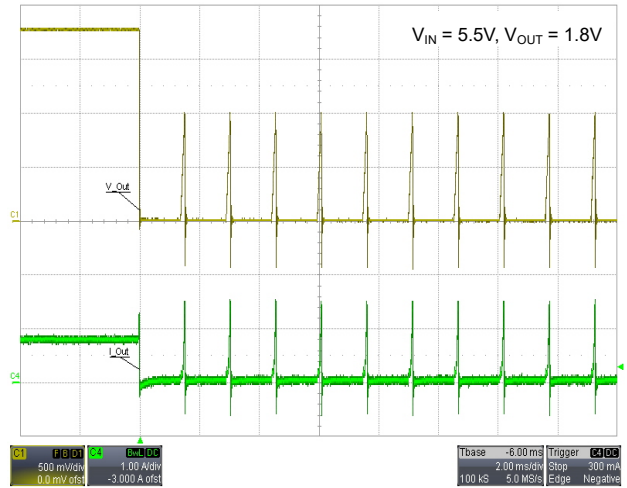
Combined Line/Load Transient



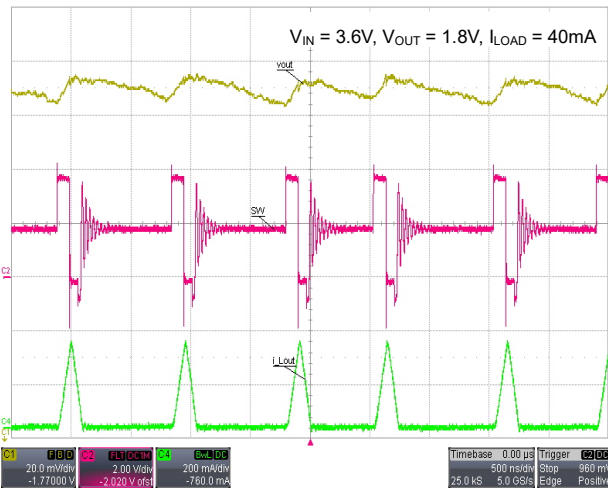
OCP Hiccup



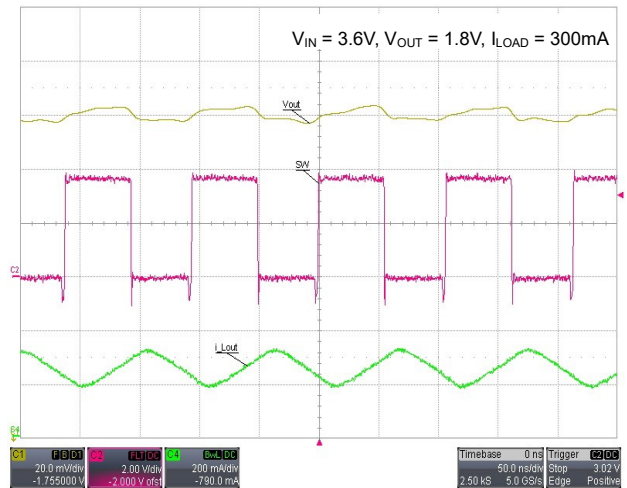
OCP Hiccup



PFM Mode Operation



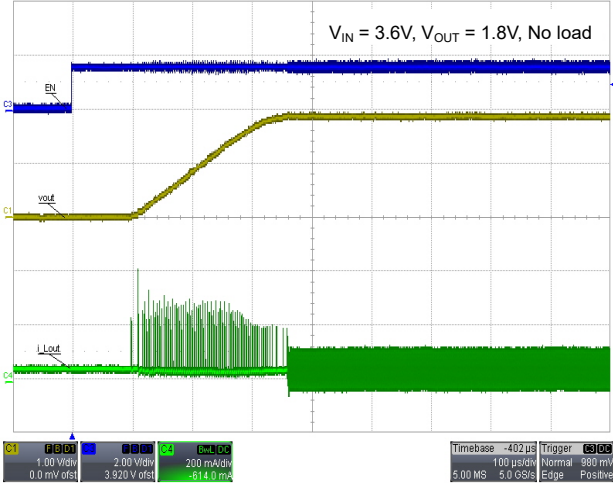
PWM Mode Operation



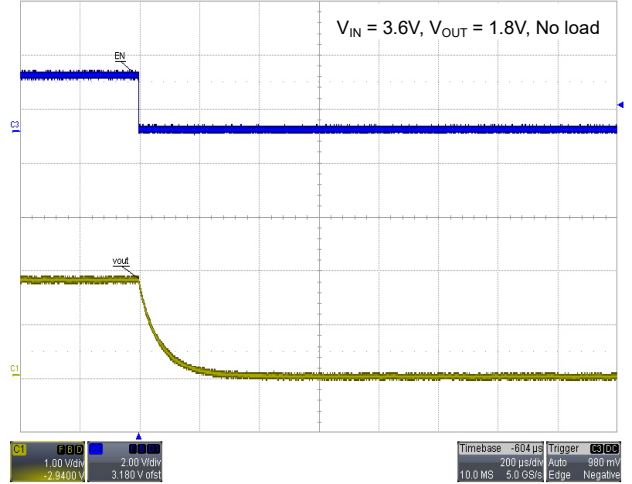
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

$V_{IN} = 3.6V$, $V_{OUT} = 1.8V$. MODE = 0V, $T_A = +25^\circ C$. $F_{SW} = 10MHz$ for 1.8V device, $F_{SW} = 6.5MHz$ for 1.2V and $F_{SW} = 8MHz$ for 3.3V devices, unless otherwise noted.

Start-up, Mode = High



Shutdown, Mode = High



FUNCTIONAL BLOCK DIAGRAM

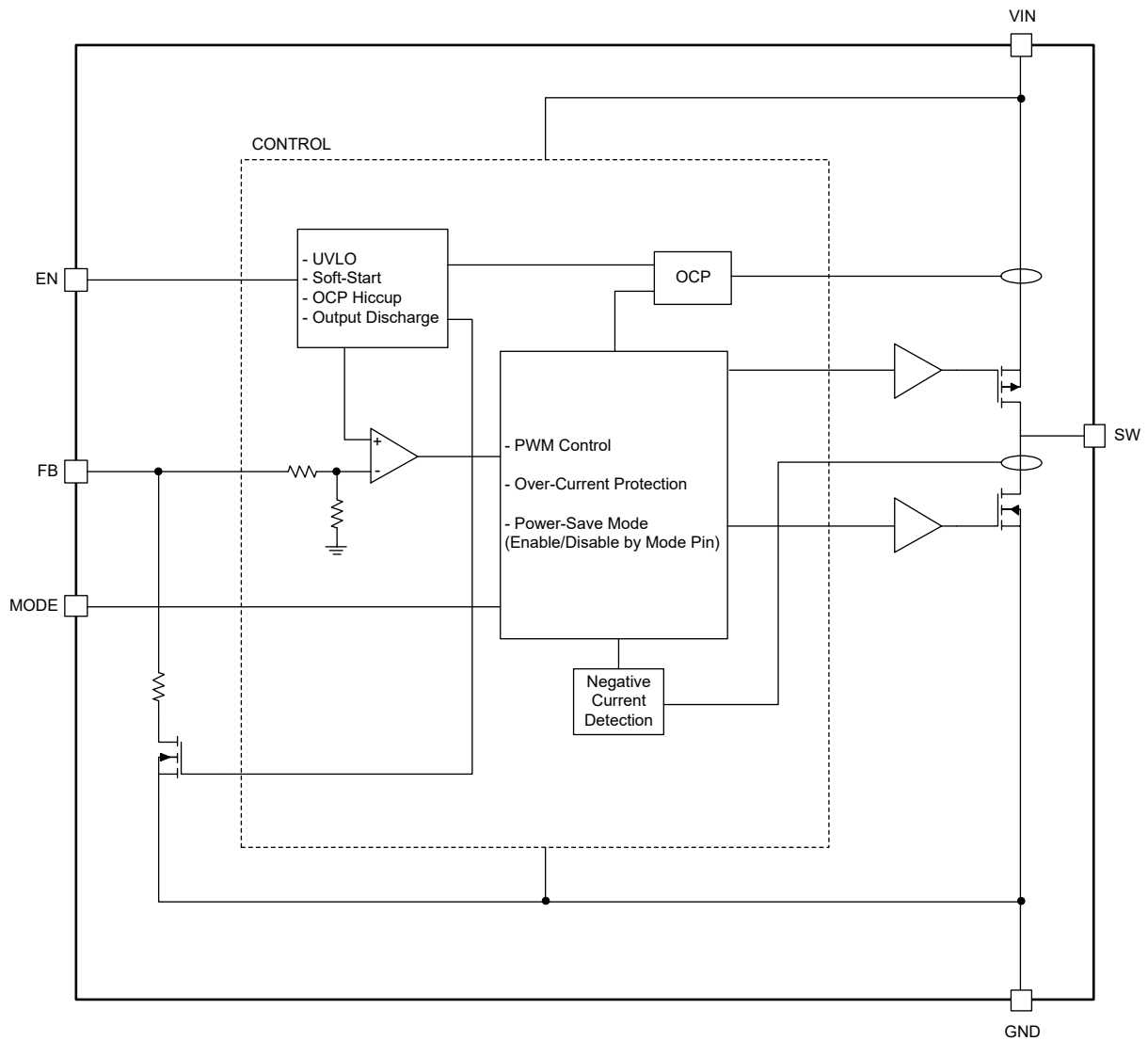


Figure 2. Block Diagram

DETAILED DESCRIPTION

The SGM61013 family is synchronous Buck DC/DC converters with switching frequency up to 10MHz. Operating from an input voltage between 2.3V and 5.5V, the converter can deliver up to 1A load current at a fixed output voltage.

Under-Voltage Lockout (UVLO)

The under-voltage lockout feature prevents the device from turning on if V_{IN} is below the UVLO level of 2.0V. If the device is enabled under UVLO conditions, the circuitry will not turn on until the input voltage is increased. Once it is active, the UVLO circuit has 150mV of hysteresis and the device will turn off if V_{IN} drops below 1.85V.

Enable

Setting the EN voltage to logic high enables the device. Alternatively, the device is disabled when the EN voltage is set to logic low. In this state, the IC draws less than 1 μ A of current and the output is pulled down to ground through a resistive load (R_{DSON}). V_{OUT} starts to ramp up after 100 μ s delay.

Soft-Start

When the device is enabled, internal soft-start circuitry causes V_{OUT} to ramp up over a period of 280 μ s to limit inrush current. This feature protects a high impedance source from being pulled to a lower voltage as the device turns on.

Active Output Discharge

When the device is disabled through the EN pin, a discharge path for the output capacitor is created between V_{OUT} and ground through a 17 Ω resistor (R_{DIS}).

Modes of Operation

The MODE pin selects the device's mode of operation. When connected to logic high, the converter always

operates in pulse width modulation (PWM) mode regardless of load current. The PWM mode is a continuous switching mode where the duty cycle is modulated to achieve the required output power.

When connected to logic low, the converter automatically switches to pulse frequency modulation (PFM) mode at light current loads. In PFM mode the frequency of pulses is varied to deliver the best possible efficiency. The device switches between PFM and PWM as the load current changes and thus optimizes performance.

If the input voltage ever gets too close to the target output voltage, such that regulation can no longer be maintained, the converter will enter 100% duty cycle mode. In this mode the high-side switch is on, connecting the input and output together to deliver a voltage as close to the target as possible.

Over-Current Protection

The device has an over-current protection to prevent damage to the device and inductor during over-current conditions.

Over-current protection occurs at 1.6A. After hitting 16 consecutive cycles of peak current limit, the output will be disabled. After being disabled for 1.5ms, the device will be re-enabled, and a new soft-start cycle will begin.

Thermal Shutdown

The device thermal shutdown protection is enabled if the chip temperature exceeds +135 $^{\circ}$ C. Once the temperature drops below +120 $^{\circ}$ C, the device will be re-enabled, and a new soft-start cycle will begin.

APPLICATION INFORMATION

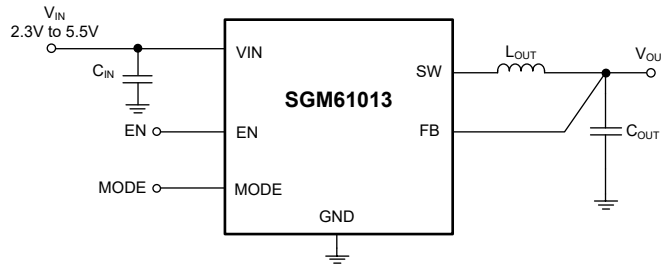


Figure 3. Application Circuit

Table 1 .Recommended Components

Part	Value	Package	Manufacturer	Part Number
C _{IN}	4.7μF, 10V	0402	AVX	0402ZD475MATA2A
	2.2μF, 10V	0402	AVX	0402ZD225MATA2A
C _{OUT}	4.7μF, 10V	0402	AVX	0402ZD475MATA2A
	2.2μF, 10V	0402	AVX	0402ZD225MATA2A
L _{OUT}	470nH, DCR 54mΩ	1.6mm × 1.0mm × 0.8mm	Murata	DFE18SANR47MG0L
	470nH, DCR 32mΩ	2.0mm × 1.6mm × 1.0mm	Murata	DFE201610ER47M
	470nH, DCR 40mΩ	2.0mm × 1.6mm × 1.0mm	FDK	MIPSZ2016DR47FR
	470nH, DCR 125mΩ	1.6mm × 0.8mm × 0.6mm	Cyntec	16010F100E
	470nH, DCR 80mΩ	2.0mm × 1.2mm × 1.0mm	Sunlord	MPH201210QR47MT

Layout Guidelines and Example

A well-designed and manufactured PCB is important for all switching power supplies, especially for those operate at high switching frequency.

Poor layout could result in system instability, EMI failure, and device damage. Hence, care must be taken in board layout to achieve the specified performance.

Please use the following guidelines when designing PCBs:

- Keep components placement as compact as possible.
- Place a low-ESR input capacitor as close to VIN and GND as possible.
- Minimize the area between SW pin trace and inductor to limit high frequency radiation.
- Keep FB trace away from noisy components and traces (e.g. SW and inductor).
- Use wide and short traces for the main current paths.
- Ground pins of converter must be strongly connected to PCB ground with low inductance and impedance.

- Place common and unbroken ground for C_{IN} and C_{OUT}.
- Reduce excessive thermal relief vias and keep them away from SW and inductor.

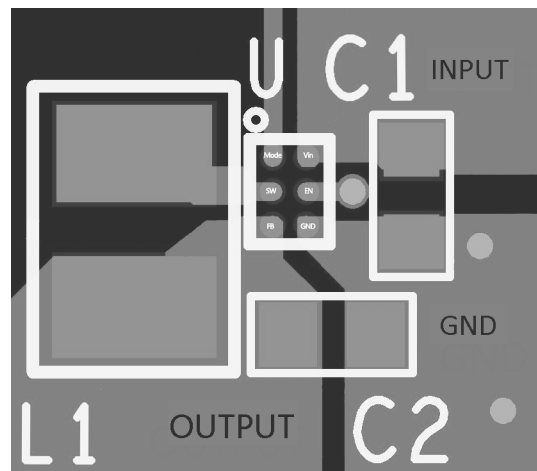


Figure 4. Layout Top Layer

REVISION HISTORY

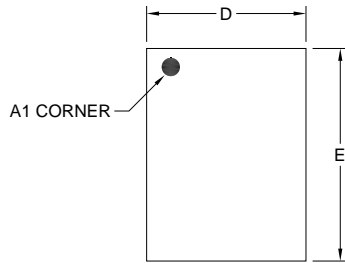
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DECEMBER 2022 – REV.A to REV.A.1	Page
Updated fixed output voltage options.....	1, 2

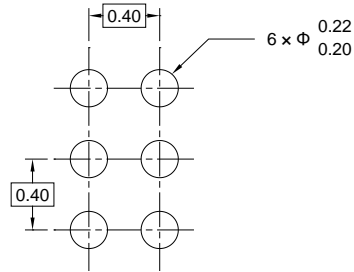
Changes from Original (NOVEMBER 2022) to REV.A	Page
Changed from product preview to production data.....	All

PACKAGE OUTLINE DIMENSIONS

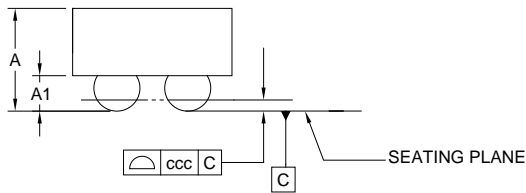
WLCSP-0.9x1.2-6B



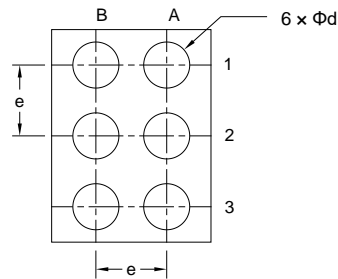
TOP VIEW



RECOMMENDED LAND PATTERN (Unit: mm)



SIDE VIEW



BOTTOM VIEW

Symbol	Dimensions In Millimeters		
	MIN	MOD	MAX
A	0.536	0.582	0.628
A1	0.182	0.202	0.222
D	0.860	0.900	0.940
E	1.160	1.200	1.240
d	0.223	0.262	0.301
e	0.400 BSC		
ccc	0.030		

NOTE: This drawing is subject to change without notice.

PACKAGE INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
WLCSP-0.9×1.2-6B	7"	9.5	0.99	1.38	0.69	4.0	4.0	2.0	8.0	Q1

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PACKAGE INFORMATION

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
7" (Option)	368	227	224	8
7"	442	410	224	18

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